

DEVICE COMPONENTS

CPU

Name: NXP/Freescale i.MX6 SoloX CPU
Type: ARM CortexTM-A9 + ARM Cortex-M4 CPU
Cores: Single Core CortexTM-A9
 + ARM CortexTM-M4 CPU Clock

ETHERNET

Number of Ports: 2
Type: 10 / 100 / 1 GB

ANTENNAS

Custom antenna solutions available

Compatible Wireless Technologies:
 LTE / LTE+ / HSPA / GSM / CDMA /
 DCS / PCS / WCDMA / UMTS / GPRS /
 EDGE / GPS

Compatible Frequencies:
 698~960 / 1575.42 / 1710~2700 / 5150~5850 MHz

Connection Type: 9x SMA-female

SAMPLE MODEMS

Customized connectivity solutions available for desired band coverage.

Example configuration for maximum speeds in North America

MODEMS	FOUR IDENTICAL MODEMS
BANDS:	LTE-FDD: B2, B4, B5, B7, B12, B13, B17, B25, B26, B29, B30, B66 LTE-TDD: B41 WCDMA: B2, B4, B5
SPEED (CAT 6):	Maximum bonded speed: 1 Gbps downlink, 200 Mbps uplink.* Maximum speed per modem: 300 Mbps downlink, 50 Mbps uplink.

Example configuration for true global coverage

MODEMS	EMEA, AUS	N. AMERICA	LATAM	APAC
BANDS:	LTE-FDD: B1, B3, B5, B7, B8, B20, B28, B32 LTE-TDD: B38, B40, B41 WCDMA: B1, B3, B5, B8	LTE-FDD: B2, B4, B5, B7, B12, B13, B17, B25, B26, B29, B30, B66 LTE-TDD: B41 WCDMA: B2, B4, B5	LTE-FDD: B2, B3, B4, B5, B7, B8, B20, B28 LTE-TDD: N/A WCDMA: B2, B3, B4, B5, B8	LTE-FDD: B1, B3, B5, B7, B8, B18, B19, B21, B26 LTE-TDD: B38, B39, B40, B41 WCDMA: B1, B5, B6, B8, B9, B19
SPEED (CAT 6):	Maximum bonded speed: 1 Gbps downlink, 200 Mbps uplink.* Maximum speed per modem: 300 Mbps downlink, 50 Mbps uplink.			

* Maximum speed based on Cat 6 LTE limits. Bonded speeds assume LTE bands are available for all modems in a given region.

WEIGHT AND DIMENSIONS

482 grams or 1 lb 1 oz
 16 x 18 x 4 cm or 6.2 x 7.2 x 1.5 in

POWER REQUIREMENTS

5 V, Peak 20 W

OPERATING TEMPERATURES

CPU: Commercial: 0°C to 70°C
 Industrial: -40°C to 85°C
MODEMS: -40°C to 85°C



For more information, visit www.telna.com
 or email iot@telna.com